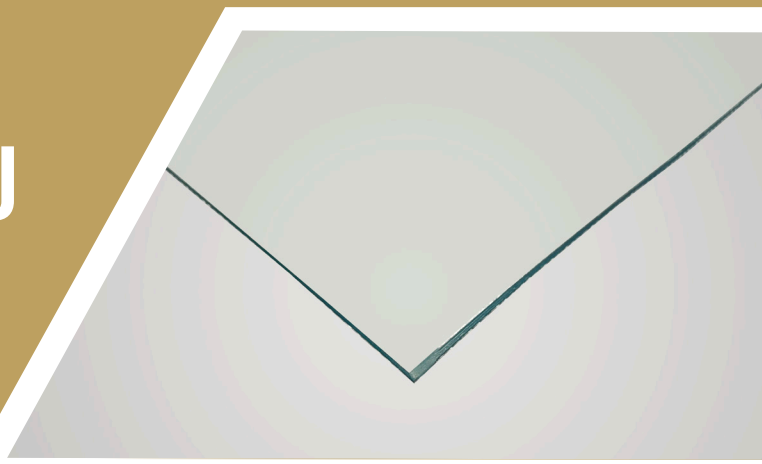
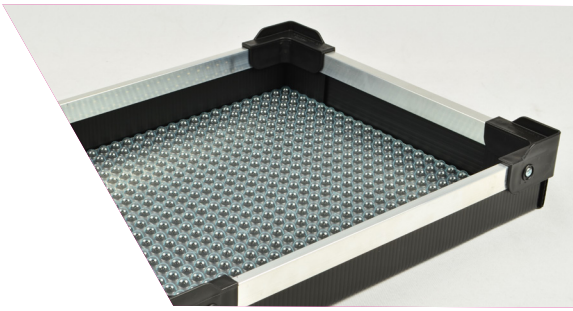
KLEANSTAT™ FLEX TPU



PN: KLEANSTAT™ FLEX TPU

DESCRIPTION: Inherently Dissipative TPU | Permanent
APPLICATION: Long-Term Use | Thermoforming



MATERIAL INFO

Kleanstat™ Flex (KSF) TPU is flexible and durable permanent static dissipative material that can be thermoformed or die cut. KSF can be cleaned with IPA with no effect on ESD properties. This material is excellent for long term clean room or any FOD free application. CCI forms KSF into our proprietary cushioning bubbles. The bubble cushioning repeatedly rebounds for great FOD free cushioning.

CHARACTERISTICS

- Inherently static dissipative
- 10^8 – 10^{10} resistance
- Thermoformable
- Semi- transparent
- Low FOD – IPA cleanable

APPLICATIONS

- Medical device packaging
- Low FOD cushioning
- Clean room curtains
- Soft cell pouches for totes
- Replace foam for cushioning

SPECIFICATIONS

PROPERTY	VALUE (U.S.)	TEST METHOD
Color	Transparent	Visual
Static Decay Rate (+5000V-50V)	.01 sec	FTMS 101-C (12% RH)
Resistance		
Volume Resistance	10^8 x 10^{10} Ohms/cm	ANSI/ESD STM 11.12-2021
Surface Resistance	10^8 x 10^{10} Ohms/sq	ANSI/ESD STM 11.11-2022

All values are for pre-formed materials. Electrical values will vary with each individual design.

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